AMENDMENTS TO THE SPECIFICATION:

Please insert the following paragraph before paragraph [0001] on page:

-- This application claims priority to Japanese Patent Applications Nos. 2003-00648, 2003-00649, 2003-154602, 2003-154604. The entire disclosure of Japanese Patent Nos. 2003-00648, 2003-00649, 2003-154602, 2003-154604 is hereby incorporated herein by reference. --

Please replace the paragraph [0008] with the following rewritten version:

-- A braking device for a dual bearing reel according to the first aspect of the present invention is a device that brakes a spool that is rotatively mounted to a reel unit, and includes a spool braking unit and a spool control unit. The spool braking unit serves to brake the spool, and includes a rotor element, a plurality of serially connected coils, and switch means. The rotor element rotates together with the spool and includes a plurality of magnetic poles arranged around the rotational direction of the rotor such that the polarities of the magnetic poles are sequentially different. The plurality of serially connected coils is disposed around a periphery of the rotor element in a circumferential direction. The switch means is connected to both ends of the plurality of the serially connected plurality of coils. The spool control unit electrically controls the spool braking unit, [[unit ,]] and includes a circuit board on which the switch means and the plurality of coils are installed and which is mounted on a surface of the reel unit that the surface faces one end surface of the spool, and a control element that is mounted on the circuit board. --

Please replace the paragraph [0089] with the following rewritten version:

-- The circuit board 70 is a washer-shaped and ring-shaped substrate having a circular opening in the center thereof, and is disposed on the outer peripheral side of the bearing accommodation portion 14 ~~such that~~ so as to be substantially concentric with the spool shaft 20. The circuit board 70 is fixedly coupled to the inner side surface of the wall portion 13a of the spool support portion 13 by screws. When the circuit board 70 is to be coupled with screws, then for example a jig that is temporarily positioned on the bearing accommodation

portion 14 is used to center the circuit board 70, and the circuit board 70 is then disposed so that it is substantially concentric with respect to the spool shaft 20. In this way, when the circuit board 70 is mounted to the spool support portion 13, the coils 62 that are fixedly attached to the circuit board 70 will be disposed so that they are substantially concentric with the spool shaft axis. --

Please replace the paragraph [00124] with the following rewritten version:

-- In the first embodiment, the insulating coating film 90 is formed on the whole surface of the circuit board 70. However, it is possible to form insulating coating selectively. The description below abbreviates the explanation of ~~identical or equal~~ constitution and operation that are identical or equal with those of the first embodiment ~~at the time of explaining later~~. --

Please replace the paragraph [00125] with the following rewritten version:

-- As shown in Figures 12-14A, 14B, in the second embodiment, the switch element 63 includes, for example, two parallel connected FET (field effect transistors) 63a that can switch on and off at a high speed. The serially connected coils 62 are connected to each drain terminal of the FET 63a. As shown in Figure 14B, the switch element 63 is mounted to the rear surface of the circuit board 70 (the surface on the opposite side of the front surface facing the flange portions 12a). --

Please replace the paragraph [00138] with the following rewritten version:

-- As shown in Figures 16 and 17A, 17B, in the third embodiment, the switch element 63 includes, for example, two parallel connected FET (field effect transistors) 63a that can switch on and off at a high speed. The serially connected coils 62 are connected to each drain terminal of the FET 63a. As shown in Figure 17B, the switch element 63 is mounted to the rear surface of the circuit board 70 (the surface on the opposite side of the front surface facing the flange portions 12a). --

Please replace the paragraph [00141] with the following rewritten version:

-- Note that the rectifier circuit 58 and the electricity storage element 57 are both provided on the circuit board 70. As shown by the dots in Figures 16 and 17A, 17B, both the circuit board 70 and the electrical components mounted on both sides thereof (such as the microcomputer 59) are covered with a molded insulating coating film 290 (another example of the first synthetic resin coating film ~~rilm~~) made from a synthetic resin insulating material that is colored such that ~~that~~ light will only partially pass through the molded insulating coating film 290. The molded insulating coating film 290 is formed by a hot melt molding process. In the hot melt molding process, a resin raw material is injected into a mold 101 (Figure 18) in which a circuit board 70 having electrical components such as the microcomputer 59 and electro-optical sensors 44, 45a, 56b is set. However, the molded insulating coating film 290 is not formed on the front and rear sides of regions 95 on which head portions 92a of the screws 92, or the light emitter portions of the light emitters 44a, 56c and receptor portions of the receptors 44b, 56d of the electro-optical sensors 44, 55a, 56b are to be disposed. In addition, the molded insulating coating film 290 is not formed on a region on which an external device connector 96 is formed. This way, it is possible to eliminate the task of removing the molded insulating coating film 290 when using each connecting point 96a-96d on the external device connector 96 to inspect whether or not the circuit is normal during the manufacture of the circuit board 70. Note that when the inspection of the circuit is completed, an insulating coating film 290 is formed by, for example, a hot melt spray process on the region on which the external device connector 96 was formed. --

Please replace the paragraph [00147] with the following rewritten version:

-- As shown in Figure 17B, on the rear surface of the circuit board 70, the molded insulating coating film 290 is ~~are~~ formed with different thicknesses on three regions. The three regions including an inclined first region 98a that has, for example, thicknesses of 2.2 mm and 1.8 mm and on which the two electro-optical sensors 56a, 56b are disposed, a second region 98b that is divided into two portions [[,]] and has, for example, a thickness of 2.8 mm, and on which the microcomputer 59 and the switch element 63 are disposed, and a third region 98c that has, for example, a thickness of 1 mm. --

Please replace the paragraph [00147] with the following rewritten version:

-- A water-repelling layer is formed on the inner peripheral surfaces of the tubular portions of the molded insulating coating film 290 and on the light emitters and receptor portions by, for example, spraying a water repellant layer thereon. Thus, it will be difficult for moisture to remain because the light emitter and receptor portions are surrounded with tubular shapes, even if moisture adheres to the inner peripheral surfaces of the tubular portions. Thus, contamination caused by the deposit of impurities contained in moisture can be controlled, and declines in the light reception/emission efficiency of the light emitter portions and the receptor portions ~~of the lights and receptors~~ caused ~~cause~~ by this contamination can be controlled. --

Please replace the paragraph [00157] with the following rewritten version:

-- In the aforementioned ~~the~~ third embodiment, an insulating coating film is simply formed on the external connector 96 by a hot melt spray process after the molded insulating coating film 290 is formed. However, as shown in Figure 21, a non-molded insulating coating film 298 (an example of second synthetic resin coating film) may also be formed on the surface of the molded insulating coating film 290 by an immersion process. The non-molded insulating coating film 298 is formed in the following manner. When the inspection of the circuit is completed, the regions 95 in which the head portions 92a of the screws 92 are disposed, and the light emitter portions of the light emitters 44a, 56c and the receptor portions of the receptors 44b, 56d of the electro-optical sensor 44, 56a, 56b are masked with tape or by printing. Then, the masked circuit board 70 is immersed in a tank which contains a liquid synthetic resin, and the masked circuit board 70 is then removed from the tank and subjected to a hardening process in order to form the non-molded insulating coating film 298 on the surface of the masked circuit board 70. --

Please replace the paragraph [00161] with the following rewritten version:

-- (b) In the aforementioned embodiment, the rotor element 60 was constructed by a plurality of magnets 61. However, for example, the rotor element 60 may be unitarily formed with a tubular plastic magnet or the like having a rare earth metal if the tubular plastic magnet includes magnetic poles that are sequentially disposed such that ~~that~~ their polarities are different in the peripheral direction. --

Please delete paragraph [00170].